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(54) OPTICAL MODULE, WAFER SCALE PACKAGE, AND METHOD FOR MANUFACTURING THOSE

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(57) ABSTRACT

An optical module for an electro-optical device with a functional element, in particular for a camera device, and to an electro-optical device with such a module. The optical module includes a lens substrate portion with at least one lens element, and a spacer. The spacer serves to keep the lens substrate at a well defined axial distance from a base substrate portion of the fully assembled electro-optical device. In order to ensure improved performance of the functional element, an EMC shield is provided. The spacer is at least in parts electrically conductive and thus forms the EMC shield or a part thereof. A method of manufacturing a plurality of such modules on a wafer scale is also provided.

